

Rectifier Diodes

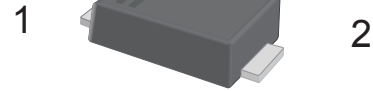
S2AF ~S2MF

■ Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives



SOD-123FL



Top View

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	Unit
Repetitive Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
RMS Voltage	VRMS	35	70	140	280	420	560	700	
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	
Forward Voltage @ IF=2A	VF	1.1							A
Averaged Forward Current.Ta=65℃	IFAV	2							
Peak Forward Surge Current @ 8.3ms	IFSM	60							
Maximum DC Reverse Current Ta=25℃ Ta=125℃	IR	5							μA
		50							
Typical Junction Capacitance (Note.1)	Cj	30							pF
Typical Thermal Resistance	RθJA	50							℃/W
Junction Temperature	TJ	150							℃
Storage Temperature	Tstg	-55 to 150							

Note.1: Measured at 1MHz and applied reverse voltage of 4V D.C

■ Marking

NO.	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF
Marking	2A1	2A2	2A3	2A4	2A5	2A6	2A7

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■ Typical Characteristics

Fig.1 Forward Current Derating Curve

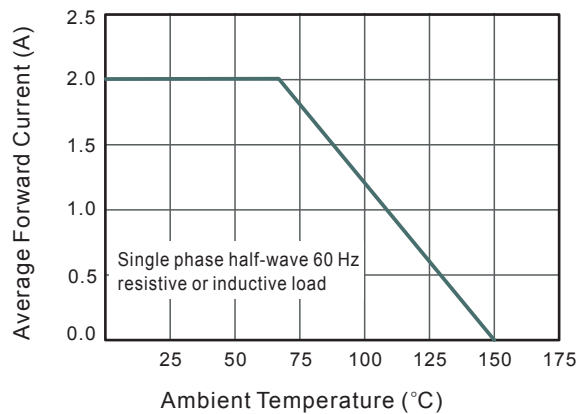


Fig.2 Typical Instantaneous Reverse Characteristics

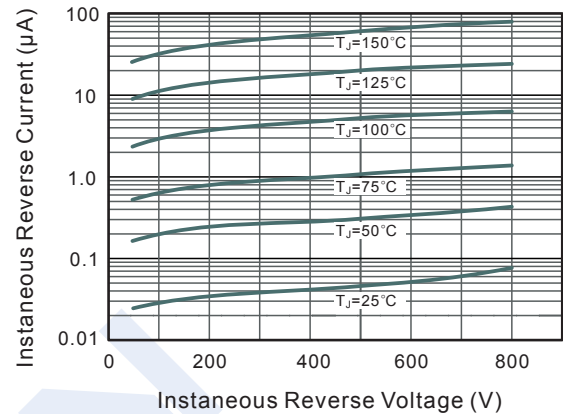


Fig.3 Typical Forward Characteristic

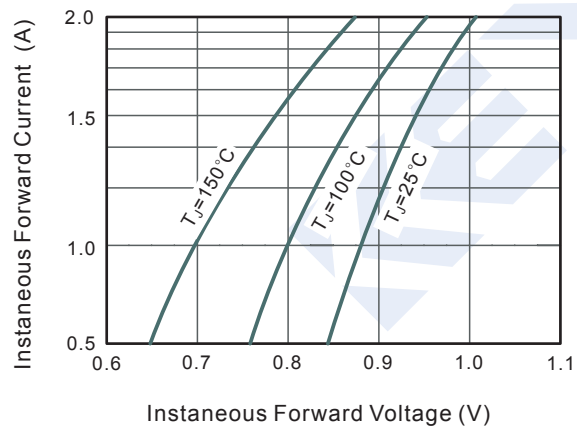
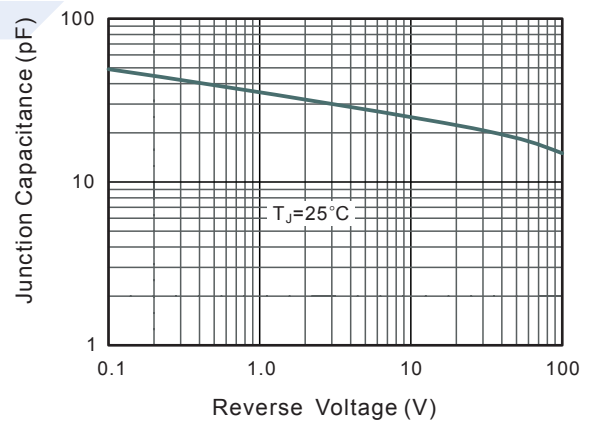


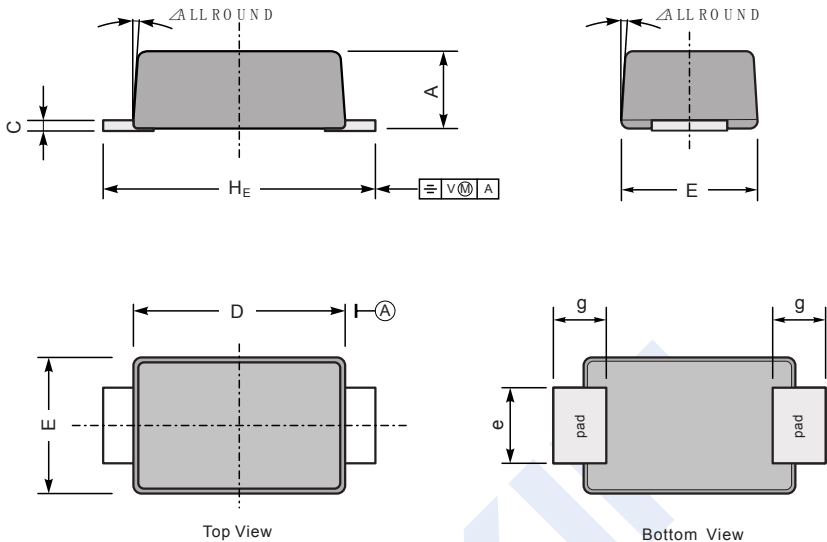
Fig.4 Typical Junction Capacitance



PACKAGE OUTLINE

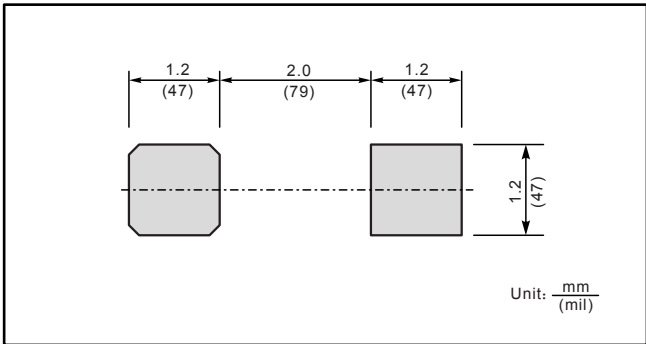
Plastic surface mounted package; 2 leads

SOD-123FL



UNIT		A	C	D	E	e	g	H _E	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size



Unit: $\frac{\text{mm}}{(\text{mil})}$